## PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2894

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF

MANUFACTURING THE PACKAGE

## REQUEST FOR ORAL HEARING

## MAIL STOP APPEAL BRIEF - PATENTS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Appellant hereby requests an Oral Hearing in the above-identified application before the Patent and Trademark Office Board of Patent Appeals and Interferences.

The USPTO is directed and authorized to charge the statutory fee of \$1080.00 and all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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23373 CUSTOMER NUMBER

Date: October 22, 2009